

Using the ROM Image on DA830 with RTSC Content

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ABSTRACT

The Primus DA830 device includes DSP/BIOS 6 in its on-chip ROM. Placing DSP/BIOS 6 in the ROM frees RAM space and improves performance, but sacrifices some configurability. This document explains how to use the DSP/BIOS ROM image in an application.

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1 Introduction

The Primus DA830 device includes DSP/BIOS 6 in its on-chip ROM. Placing DSP/BIOS 6 in the ROM frees RAM space and improves performance, while sacrificing some configurability. The main limitation when configuring against a ROM image is that some RTSC module configuration parameters are “frozen” when the ROM was created, and cannot be modified.

RTSC is a standard for reusable software components. XDCtools is a set of tools that enable the creation and use of RTSC packages.

2 Using the DSP/BIOS ROM Image

To use the DSP/BIOS ROM, add a single line to your application’s RTSC configuration file (.cfg file). *The following line must be the first line in your .cfg file:*

```
Program.importRomAssembly(`ti.sysbios.rom.da830.romimage`);
```

The rest of your RTSC configuration script will most likely remain unchanged.

Including the “Program.importRomAssembly” command causes the RTSC configuration to bring in the ROM assembly, and any DSP/BIOS code you reference will be referenced from the ROM.

The DSP/BIOS 6 ROM code, and all of the read/write data structures that support the ROM code are located at the addresses shown in the following table.

Resource	Address
ROM code	0x11700200
RAM data structures	0x11800020

2.1 Modules in the ROM

The ROM image contains a set list of DSP/BIOS modules, shown in the following table. If your application uses modules that are not in this list, they will be brought into RAM.

Table 1. ROM modules

ti.sysbios BIOS	ti.sysbios.knl Clock Idle
ti.sysbios.family.c62 IntrinsicSupport TaskSupport	Swi Task
ti.sysbios.family.c64p Cache Exception Hwi TimestampProvider	ti.sysbios.misc Intrinsic Queue
ti.sysbios.family.c64p.primus TimerSupport	ti.sysbios.timers.timer64 Timer
ti.sysbios.gates GateHwi GateMutex	xdc.runtime Assert Core Defaults Diags Error Gate Log LoggerBuf Main Memory Startup SysMin System Text Timestamp
ti.sysbios.hal Hwi Timer	
ti.sysbios.heaps HeapMem	
ti.sysbios.ipc Event Semaphore	

2.2 Frozen Module Configuration Parameters

There is an important limitation to consider when using the ROM image. Many of the module configuration parameters for the modules in the ROM image have been “frozen” to specific (usually default) values, and cannot be changed by your configuration.

The reason for this is an important optimization in RTSC code generation. When XDCtools generate code based on the client’s configuration, the module configuration parameters are generated as constants. The compiler can then fold these constants into the code, so that the code is optimized as though it were written specifically for the client’s configuration.

When the ROM image is generated, the code is frozen. So, to benefit from this important optimization, the values of the module configuration parameters must be decided on and “sealed”.

If you attempt to modify a configuration parameter that has been frozen, you will receive a configuration error message. The following example shows an error message that results from an attempt to modify the parameter Semaphore.supportsEvents, which has been frozen in the ROM image.

```
configuring SemaphoreTest.p674 from package/cfg/SemaphoreTest_p674.cfg ...
js: "./SemaphoreTest.cfg", line 13: ti.sysbios.ipc.Semaphore: 'supportsEvents' is
sealed
```

Table 2 lists all of the module configuration parameters in the ROM. In general, configuration parameters that are critical to DSP/BIOS performance are frozen in the ROM image, while non-critical parameters are still configurable. Parameters that are frozen are highlighted in **blue**. For modules in the ROM, all proxies have been bound and cannot be changed.

Some of the frozen module configuration parameters have been set to a value other than the default. These are described later in this document, along with an explanation of the value chosen for each.

For more information on a configuration parameter and its default value, refer to the module’s online help reference documentation.

Table 2. Configuration Parameters for Modules in the ROM.

<p>ti.sysbios</p> <p>BIOS cpuFreq taskEnabled swiEnabled clockEnabled rtsGateType startupFxn[]</p> <p>ti.sysbios.family.c64p</p> <p>Cache EMIFA_BASE EMIFA_LENGTH EMIFB_BASE EMIFB_LENGTH EMIFC_BASE EMIFC_LENGTH EMIFA_CFG EMIFB_CFG EMIFC_CFG initSize MAR0_31 MAR32_63 MAR64_95 MAR96_127 MAR128_159 MAR160_191 MAR192_223 MAR224_255</p> <p>Exception enableExternalMPC exceptionHook internalHook externalHook nmiHook returnHook</p> <p>Hwi dispatcherAutoNestingSupport dispatcherSwiSupport dispatcherTaskSupport dispatcherIrpTrackingSupport enableException swiDisable swiRestoreHwi taskDisable taskRestoreHwi ierMask hooks[]</p>	<p>TimerSupport timer[]</p> <p>TaskSupport defaultStackSize stackAlignment</p> <p>ti.sysbios.hal</p> <p>Hwi dispatcherAutoNestingSupport dispatcherSwiSupport dispatcherTaskSupport dispatcherIrpTrackingSupport hooks[]</p> <p>ti.sysbios.ipc</p> <p>Semaphore supportsEvents eventPost eventSync</p> <p>ti.sysbios.knl</p> <p>Clock tickSource timerId swiPriority tickPeriod</p> <p>Idle funcList[]</p> <p>Swi taskDisable taskRestore numPriorities hooks[] numConstructedSwis</p> <p>Task initStackFlag numPriorities defaultStackSize defaultStackSection defaultStackHeap hooks[] idleTaskStackSize idleTaskVitalTaskFlag numConstructedTasks</p>	<p>ti.sysbios.timers.timer64</p> <p>Timer anyMask numTimerDevices timerSettings[] defaultHalf</p> <p>xdc.runtime</p> <p>Diags setMaskEnabled dictBase</p> <p>Error policy raiseHook maxDepth</p> <p>LoggerBuf enableFlush</p> <p>Memory defaultHeapInstance defaultHeapSize</p> <p>Startup maxPasses firstFxn[] lastFxn[] resetFxn</p> <p>SysMin bufSize flushAtExit outputFxn</p> <p>System maxAtexitHandlers extendFxn</p> <p>Text nameUnknown nameEmpty nameStatic isLoading</p> <p>Log.Event (all)</p> <p>Assert.Id (all)</p> <p>Error.Id (all)</p>
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2.3 Non-default Frozen Values

Most frozen module parameters are set to their default values in ROM. The following excerpt shows the frozen configuration parameters that are set to a value other than the default. These frozen parameters are shown in **blue**.

```
var System = xdc.useModule('xdc.runtime.System');
var SysMin = xdc.useModule('xdc.runtime.SysMin');
System.SupportProxy = SysMin;

var Memory = xdc.useModule('xdc.runtime.Memory');
var HeapMem = xdc.useModule('ti.sysbios.heaps.HeapMem');
var defaultHeap = HeapMem.create({size: Memory.defaultHeapSize});
Memory.defaultHeapInstance = defaultHeap;

var BIOS = xdc.useModule('ti.sysbios.BIOS');
BIOS.rtsGateType = BIOS.GateMutex;

var Timer = xdc.useModule('ti.sysbios.timers.timer64.Timer');
var Clock = xdc.useModule('ti.sysbios.knl.Clock');
Timer.anyMask = 0;
Clock.timerId = 0; // Not frozen

var Diags = xdc.useModule('xdc.runtime.Diags');
Diags.setMaskEnabled = true;

var Text = xdc.useModule('xdc.runtime.Text');
Text.isLoaded = false; // Not frozen
```

These non-default configuration settings have some implications. The preceding excerpt performs the following actions:

- Freezes the System proxy to 'xdc.runtime.SysMin'.
- Creates a default heap of type ti.sysbios.heaps.HeapMem. This cannot be replaced with another instance, however the size of this heap can still be configured. See Section 2.5, "Modifying Existing Instances".
- Assigns a ti.sysbios.gates.GateMutex instance to the runtime support library. This cannot be changed.
- Freezes Timer.anyMask to 0. This disables the "any timer" feature, and forces the user to select the timer explicitly. 'Clock.timerId' has not been frozen, but the default value has been changed from -1 ("any") to 0.
- Enables the diagnostics mask for all modules.
- Changes the default value of Text.isLoaded from true to false. This parameter is not frozen.

2.4 The “common\$” Fields

The common\$ module configuration parameters are treated specially. For modules in the ROM, these configuration parameters generally cannot be changed. Attempting to change them will not result in a configuration error, but the changes will have no effect.

For modules in the ROM, the following common\$ settings have been applied. Any changes shown here to the Defaults module effectively change the default values for the client’s configuration.

```
var Defaults = xdc.useModule('xdc.runtime.Defaults');

Defaults.common$.namedInstance = true;
Defaults.common$.namedModule = true;

Defaults.common$.instanceHeap = Memory.defaultHeapInstance.$orig;

var LoggerBufParams = new LoggerBuf.Params();
LoggerBufParams.exitFlush = true;
Defaults.common$.logger = LoggerBuf.create(LoggerBufParams);

Defaults.common$.diags_ASSERT = Diags.ALWAYS_OFF;
Defaults.common$.diags_USER1 = Diags.RUNTIME_OFF;
Defaults.common$.diags_USER2 = Diags.RUNTIME_OFF;

var GateMutex = xdc.useModule('ti.sysbios.gates.GateMutex');
var HeapMem = xdc.useModule('ti.sysbios.heaps.HeapMem');
HeapMem.common$.gate = GateMutex.create();
HeapMem.common$.fxntab = true;
```

The above configuration settings have implications *for modules in the ROM*. (All settings can be modified for modules not in the ROM.) This excerpt does the following:

- Enables module and instance names for modules in the ROM. This cannot be changed.
- Sets the default logger to a LoggerBuf instance. The logger field can be changed to point to another instance, but only another xdc.runtime.LoggerBuf instance. The parameters of this LoggerBuf instance can still be changed. See Section 2.5, “Modifying Existing Instances”.
- Sets the default instance heap (the heap used for allocating dynamically created instances) to the default heap. This can be changed.
- Sets some items in the Defaults module. In the client configuration, modifying settings for the Defaults module affects only modules not in the ROM.
- Sets diags_ASSERT to ALWAYS_OFF for the modules in the ROM. This setting cannot be changed.
- Sets diags_USER1 and diags_USER2 to RUNTIME_OFF for all ROM modules. These diagnostics can be turned on for ROM modules by setting them to RUNTIME_ON explicitly for each ROM module.
- Sets diagnostics to ALWAYS_OFF or ALWAYS_ON for ROM modules; these cannot be changed. Diagnostics set to RUNTIME_OFF can only be changed to RUNTIME_ON.

- Turns asserts off for all ROM modules; they cannot be turned on. Asserts can still be turned on for RAM modules.
- Turns Entry and Exit trace off for all ROM modules; they cannot be turned on. This is the default value. Entry and Exit trace can still be turned on for RAM modules.
- Configures HeapMem to use a GateMutex to protect its internal state and enables its function table so that it may be used abstractly as an IHeap instance. These settings cannot be changed.

2.5 Modifying Existing Instances

The ROM configuration contains a `ti.sysbios.heaps.HeapMem` instance and an `xdc.runtime.LoggerBuf` instance, which have been assigned to the `Memory.defaultHeapInstance` and `Defaults.common$.logger` fields, respectively. These instances cannot be deleted, but their properties can be modified through the `$orig` property of the fields to which they have been set.

The following example shows how to change the size of the default heap to `0x2000` by setting the `$orig.size` variable.

```
var Memory = xdc.useModule('xdc.runtime.Memory');
Memory.defaultHeapInstance.$orig.size = 0x2000;
```

To change the number of entries in the default logger to 512, set the `$orig.numEntries` variable.

```
var Defaults = xdc.useModule('xdc.runtime.Defaults');
Defaults.common$.logger.$orig.numEntries = 512;
```

2.6 Flushing LoggerBuf

The configuration parameter `LoggerBuf.enableFlush`, which flushes all logs at system exit, is frozen to its default value of `false`.

To work around this, you can use the `LoggerBuf` “flushAll” API, which you can call to manually flush the logs. To have this API called at system exit, simply add the following line of code to `main()`:

```
System_atexit(LoggerBuf_flushAll);
```

3 Conclusion

Using the DSP/BIOS 6 image in the DA830 ROM frees up RAM space and allows XDCtools to generate optimized code based on the client’s configuration. Keep in mind that the values of certain module configuration parameters that are critical to DSP/BIOS performance are frozen and cannot be changed by the user configuration, and that some of these parameters are set to non-default values.

4 References

- *XDCtools Getting Started Guide*
([xdc_install_dir/docs/XDCtools_Getting_Started_Guide.pdf](#)). Includes steps for installing and validating the installation. Provides a quick introduction to XDCtools using a "hello world" application.
- *XDCtools User's Guide*
([xdc_install_dir/docs/rtscpedia/XDCtools_User's_Guide/XDCtools_User's_Guide.html](#))

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